

**WHAT IS CLAIMED IS:**

1. A heat dissipating structure for a computer casing having a front board, a back board, and a bottom board, wherein said front board and back board are parallel and correspond to each other by being connected together on said bottom board,  
5 comprising:

two supporting frames mounted at an opposite side corresponding to said bottom board for respectively connecting with upper sides of said front board and said back board so as to form a rectangular hexahedron; and

plural placing slots mounted on said front board for placing a disk drive, a  
10 CD-ROM drive, and plural connectors therein, wherein said front board further has plural heat dissipating openings mounted thereon between positions of said placing slots.

2. The heat dissipating structure for a computer casing according to claim 1,  
15 wherein said plural heat dissipating openings are round heat dissipating openings.

3. The heat dissipating structure for a computer casing according to claim 1,  
wherein said plural heat dissipating openings are polygonal heat dissipating openings.

4. The heat dissipating structure for a computer casing according to claim 1,  
20 wherein said back board has openings and a heat dissipating fan mounted thereon, said openings are at positions corresponding to said heat dissipating fan and

parallel to said heat dissipating openings of said front board so as to help the air flowing inside said computer casing.

5. The heat dissipating structure for a computer casing according to claim 1 further comprising a housing for covering said rectangular hexahedron.

5 6. The heat dissipating structure for a computer casing according to claim 1, wherein said housing comprises a front panel, a top board and side boards, and wherein said front panel is mounted on said front board, said top board is mounted on a top of said front board, said back board, and said supporting frames and engaged with said supporting frames, and said side boards are  
10 mounted on surfaces formed by said front board, said back board, said bottom board and said supporting frames.

7. The heat dissipating structure for a computer casing according to claim 1, wherein said front panel of said housing is made of porosity material.